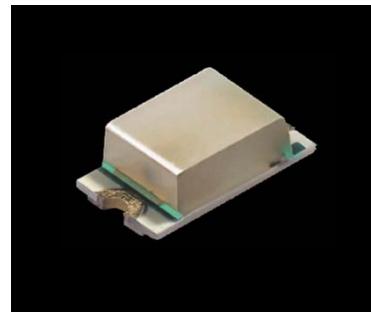


## ■ Features

- Abundant color variations with diverse luminous intensity types.

## ■ Outline

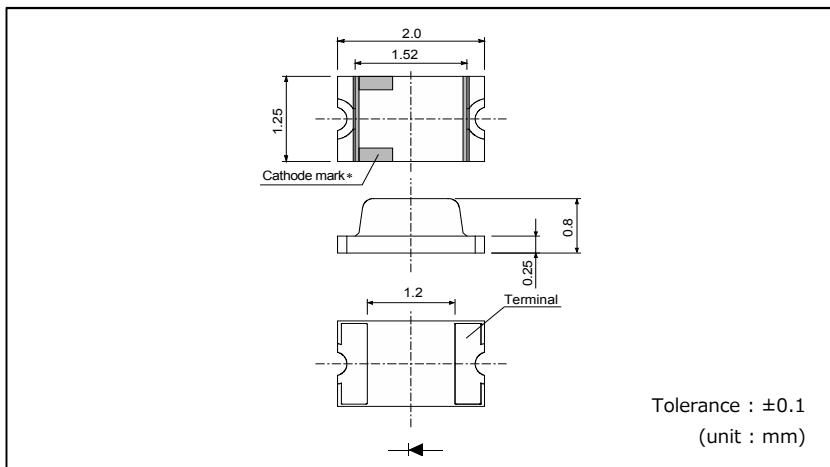


## ■ Size

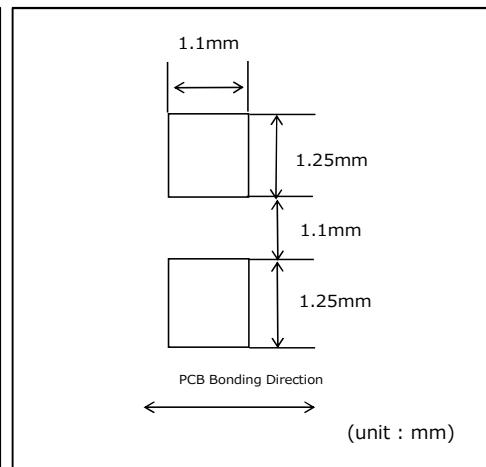
2012(0805)
2.0 × 1.25mm (t=0.8mm)



## ■ Dimensions



## ■ Recommended Solder Pattern



## ■ Specifications

Part No.	Chip Structure	Emitting Color	Absolute Maximum Ratings (Ta=25°C)						Electrical and Optical Characteristics (Ta=25°C)							
			Power Dissipation P <sub>D</sub> (mW)	Forward Current I <sub>F</sub> (mA)	Peak Forward Current I <sub>FP</sub> (mA)	Reverse Voltage V <sub>R</sub> (V)	Operating Temp. T <sub>opr</sub> (°C)	Storage Temp. T <sub>stg</sub> (°C)	Forward Voltage V <sub>F</sub> Typ. (V)	Reverse Current I <sub>R</sub> Max. (μA)	Dominant Wavelength λ <sub>D</sub> Min.*2 (nm)	Dominant Wavelength λ <sub>D</sub> Typ. (nm)	Dominant Wavelength λ <sub>D</sub> Max.*2 (nm)	Luminous Intensity I <sub>F</sub> Min. (mcd)	Luminous Intensity I <sub>F</sub> Typ. (mcd)	Luminous Intensity I <sub>F</sub> Max. (mA)
				54	20	100*1			2.2	20	625	630	635	16	25	20
SML-H12V8T	AlGaNp	Red	54	20	100*1	5	-40 ~ +85	-40 ~ +100	2.2	20	625	630	635	16	25	20
SML-H12U8T		Orange														
SML-H12D8T		Yellow														
SML-H12Y8T		Yellow Green														
SML-H12M8T		Green														
SML-H12P8T																

\*1 : Duty 1/10, 1KHz \*2 : Measurement tolerance: ±1nm

## ■ Electrical Characteristics Curves

Reference

Fig.1 Forward Current - Forward Voltages

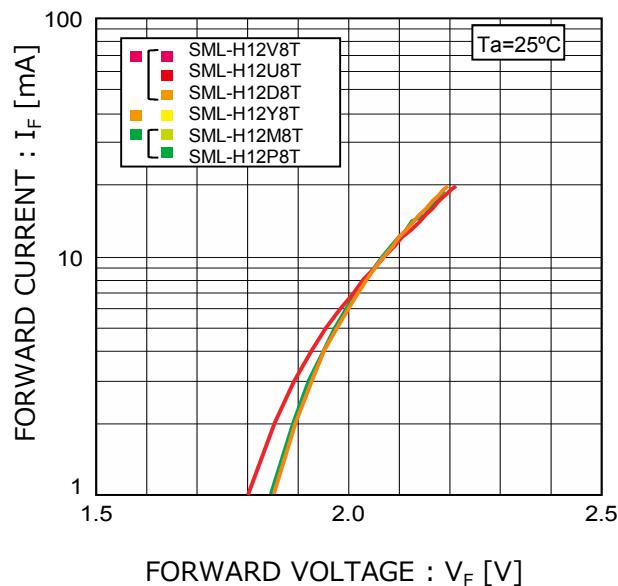


Fig.2 Luminous Intensity - Atmosphere Temperature

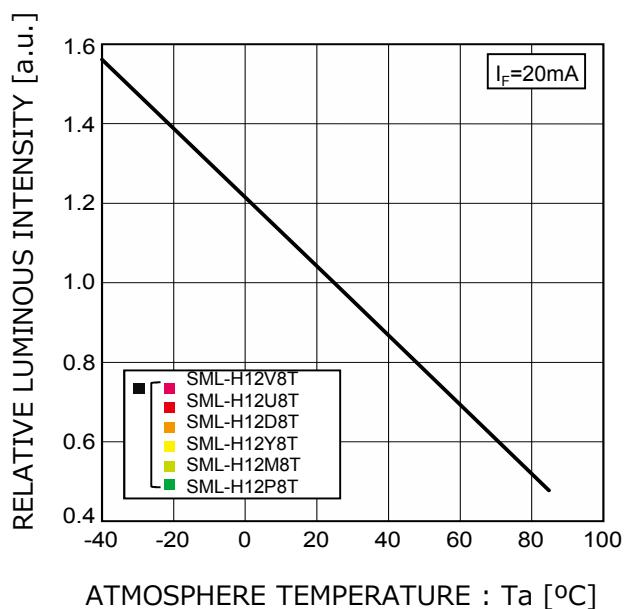


Fig.3 Luminous Intensity - Forward Current

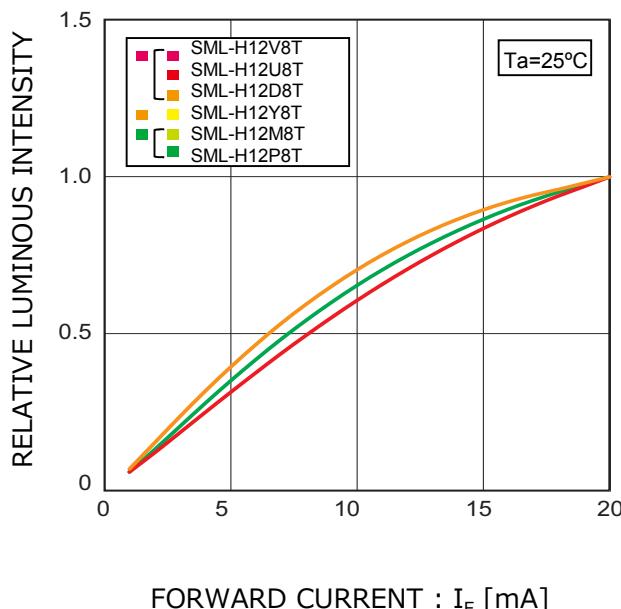
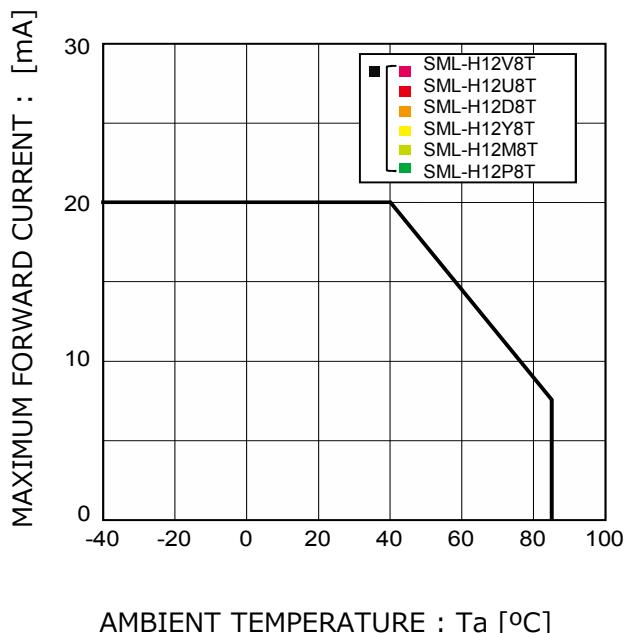
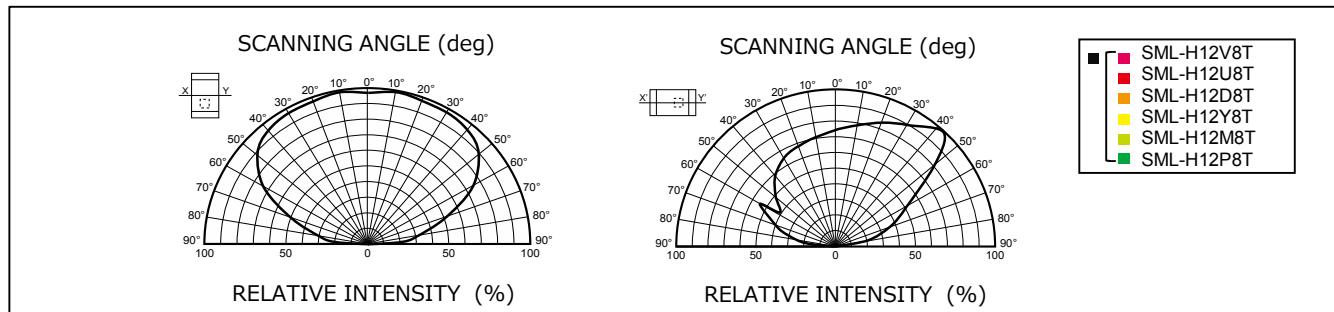


Fig.4 Derating



## ■ Viewing Angle

Reference



## ■ Rank Reference of Brightness\*

\*Measurement tolerance:±10%

## Red(V,U)

(Ta=25°C, If = 20mA)

Rank	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X	Y	Z
lv (mcd)	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630	630~1000	1000~1600	1600~2500	2500~4000
SML-H12V8T																		
SML-H12U8T																		

## Orange(D)

(Ta=25°C, If = 20mA)

Rank	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X	Y
lv (mcd)	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630	630~1000	1000~1600	1600~2500
SML-H12D8T																	

## Yellow(Y)

(Ta=25°C, If = 20mA)

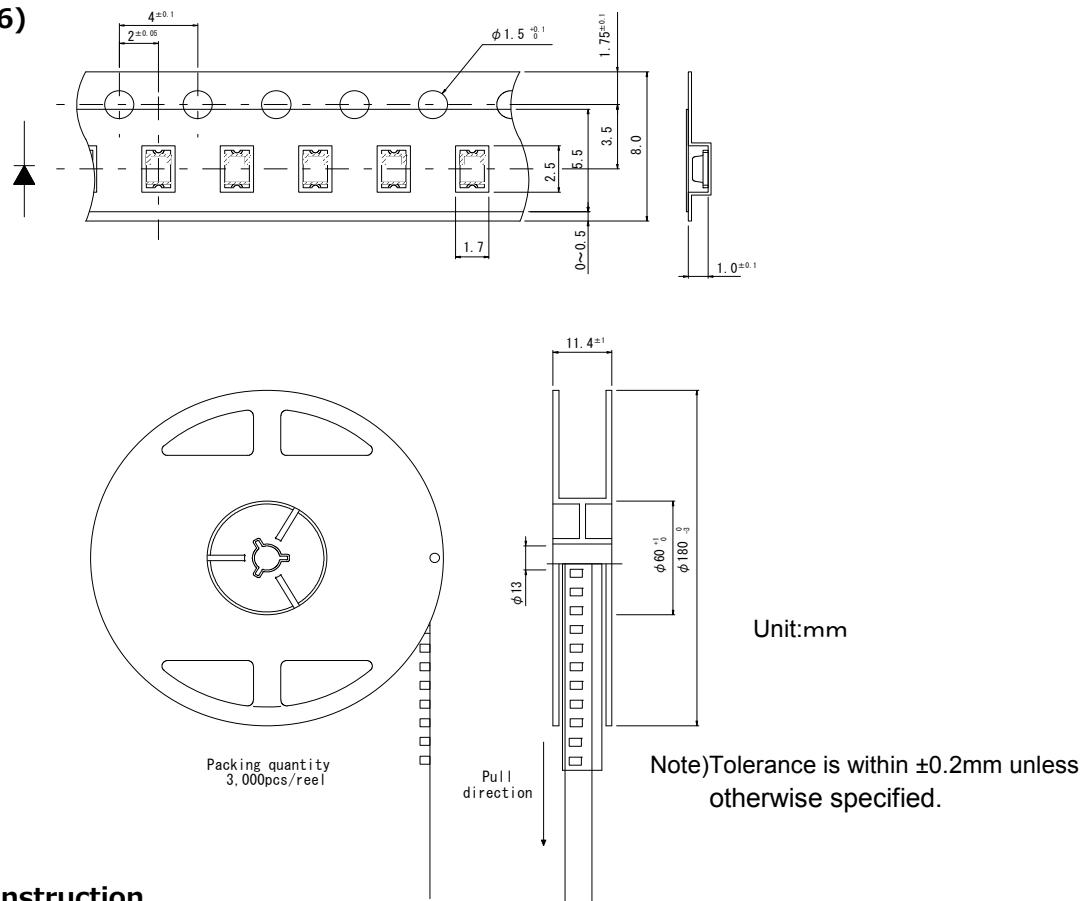
Rank	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X	Y
lv (mcd)	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630	630~1000	1000~1600	1600~2500
SML-H12Y8T																	

## Yellowish Green/Green(M, P)

(Ta=25°C, If = 20mA)

Rank	F	G	H	J	K	L	M	N	P	Q	R	S	T	U	V	W	X	Y
lv (mcd)	0.63~1.0	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630	630~1000	1000~1600	1600~2500
SML-H12M8T																		
SML-H12P8T																		

## ■ Taping (T86)



## ■ Part No. Construction

\*"- will be taken out for emitting color  
WB/B/E series.

Special Code will be applied for  
Emitting color WB/B/E series.

Chromaticity rank  
(for white LED)      Rank sign  
(Brightness Rank)\*



Series name	Package Type	Chip type	Emitting Color	Resin Color	Taping Specification
SML Chip LED	P1 1.0x0.6 t=0.2mm	0 Standard Type	V Red	T Transparent Colorless	T86 Cathode at sprocket hole side(the top)
	E1 1.6x0.8 t=0.36mm	1 Low Current Type	U Red	W Milkey White	T87 Anode at sprocket hole side(the top)
	D1 1.6x0.8 t=0.55mm	2 High Brightness type	U2 Red	B Black	1 For white LED, 3 cathode at sprocket hole side
	H1 2.0x1.25 t=0.8mm	3	D Orange		
	M1	4	Y3 Yellow		
	O1 3.0x2.0 t=1.3mm	5 Ultra High Brightness type	Y2 Yellow		
	Z1ZN 3.5x2.8 t=1.9mm	6	Y Yellow		
	A1 1.6x1.15 t=0.55mm	7	W Yellow		
	B1B2 3.4x1.25 t=1.1mm	8	M Yellowish green		
	K1 4.5x2.0 t=0.6mm		F Green		
	S1 3.2x1.6 t=1.85mm		P Green		
	P2 1.0x1.0 t=0.2mm		E Green		
	S2 1.3x1.5 t=0.6mm		B Blue		
	P34 1.0x1.0 t=0.2mm		WB White		
	P36 1.5x1.0 t=0.2mm		T Phototransistors		
	VN 3.5x2.8 t=0.6mm		RGB Red/Green/Blue		
SCM Chip LED	01 3.0x1.5 t=2.2mm				

notice) S1 series, 81 series

T86	Cathode at sprocket hole side(the back)
T68	Cathode at sprocket hole side(the top)

### ■ Precaution (Surface Mount Device)

#### 1. Storage

If the product is heated during the reflow under the condition of hygroscopic state, it may vaporize and expand which will influence the performance of the product.

Therefore, the package is waterproof. Please use the product following the conditions:

#### • Using Conditions

Classification	Temperature	Humidity	Expiration Date	Remark
① Before using	5~30°C	30~70%RH	Within 1 year from Receiving	Storage with waterproof package
② After opening package	5~30°C	Below 70%RH	Within 168h	Please storing in the airtight container with our desiccant (silica gel)

#### • Baking

Bake the product in case of below:

① The expiration date is passed.

② The color of indicator (silica gel) turned from blue to colorless or from green to pink.  
(Even if the product is within the expiration date.)

#### • Baking Conditions

Temperature	Time	Humidity
60±3°C	12~24h	Below 20%RH
Remark	<ul style="list-style-type: none"> <li>Bake products in reel.</li> <li>Reel and embossed tape are easy to be deformed when baking, so please try not to apply stress on it.</li> <li>Recommend bake once.</li> </ul>	

## 2. Application Methods

### 2-1. Precaution for Drive System and Off Mode

Design the circuit without the electric load exceeding the ABSOLUTE MAXIMUM RATING that applies on the products. If drive by constant voltage, it may cause current deviation of the LED and result in deviation of luminous intensity, so we recommend to drive by constant current.

(Deviation of VF Value will cause deviation of current in LED.) Furthermore, for off mode, please do not apply voltage neither forward nor reverse. Especially, for the products with the Ag-paste used in the die bonding, there's high possibility to cause electro migration and result in function failure.

### 2-2. Derating

The Derating Characteristics are based on the lifetime of luminous intensity and assumption of degradation & color change of sealing resin or reflector. About its reliability, please evaluate its using conditions and environment and use it after confirmed there is no problem.

### 2-3. Operation Life Span

There's possibility for intensity of light drop according to working conditions and environments (applied current, surrounding temperature and humidity, corrosive gases), please call our Sales staffs for inquiries about the concerned application below.

① Longtime intensity of light life

② On mode all the time

### 2-4. Applied Stress on Product

No resin hardening agent such as filler is used in the sealing resin of the product.

Therefore, please pay attention to the overstress on it which may influence its reliability.

### 2-5. Usage

The Product is LED. We are not responsible for the usage as the diode such as Protection Chip, Rectifier, Switching and so on.

### 3 . Others

#### 3 – 1 . Surrounding Gas

Notice that if it is stored under the condition of acid gas (chlorine gas, sulfured gas) or alkali gas (ammonia), it may result in low soldering ability (caused by the change in quality of the plating surface ) or optical characteristics changes (light intensity, chrominance) and change in quality of cause die bonding (Ag-paste) materials. All of the above will function failure of the products.

Therefore, please pay attention to the storage environment for mounted product (concern the generated gas of the surrounding parts of the products and the atmospheric environment).

#### 3 – 2 . Electrostatic Damage

The product is part of semiconductor and electrostatic sensitive, there's high possibility to be damaged by the electrostatic discharge. Please take appropriate measures to avoid the static electricity from human body and earthing of production equipment. Especially, InGaN type LEDs have lower resistance value of electrostatic discharge and it is recommended to introduce the ESD protection circuit.

The resistance values of electrostatic discharge (actual values) vary with products, therefore, please call our Sales staffs for inquiries.

#### 3 – 3 . Electromagnetic Wave

Applications with strong electromagnetic wave such as, IH cooker, will influence the reliability of LED, therefore please evaluate before using it.

## 4. Mounting

### 4-1. Soldering

- No resin hardening agent such as filler is used in the sealing resin of the product. Therefore, resin expansion and moisture absorption at humidity will cause heat stress during soldering process and finally has bad influence on the product's reliability.
- The product is not guaranteed for flow soldering.
- Do not expose the product in the environment of high temperature (over 100°C) or rapid temperature shift (within 3°C/sec. of temperature gradient) during the flow soldering of surrounding parts.
- In case of carrying out flow soldering of surrounding parts without recommended conditions, please contact us for inquiries.
- Please set appropriate reflow temperature based on our product usage conditions and specification.
- The max for reflowing is 2 times, please finish the second reflow soldering and flow soldering with other parts within the usage limitation after open the moistureproof package.
- Compare with N2 reflow, during air reflow, because of the heat and surrounding conditions, it may cause the discoloration of the resin.
- For our product that has no solder resist, because of its solder amount and soldering conditions, one of its specific characteristics is that solder will penetrate into LED. Thus, there's high possibility that will influence its reliability. Therefore, please be informed, concerning it before using it.

### 4-2. Automatic Mounting

#### 4-2-1. Silicon Resin Sealing Product

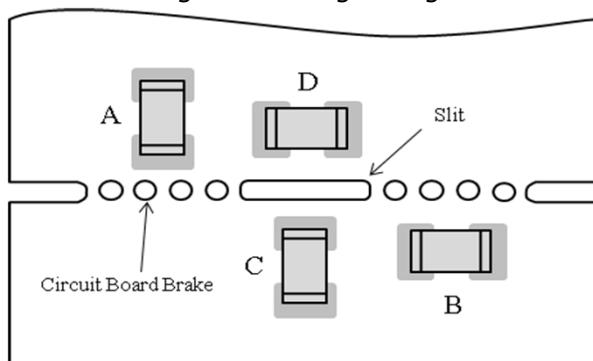
The sealing resin of LED is very soft, so please select adsorption nozzle that would not apply stress directly on the sealing section.

#### 4-2-2. Mini Package (Smaller than 1608 size)

- Vibration may result in low mounting rate since it will cause the static electricity of product and adhere to top cover tape. Therefore, the magnet should be set on parts feeder cassette of the mounter to control the product stabilization. In addition, it is recommended to set ionizer to prevent electrostatic charge.

### 4-3. Mounting Location

The stress like bending stress of circuit board dividing after mounting, may cause LED package crack or damage of LED internal junction, therefore, please concern the mounting direction and position to avoid bending or screwing with great stress of the circuit board.



Stress strength according to the mounting position:  
A > B > C > D

### 4-4. Mechanical Stress after Mounting

The mechanical stress may damage the LED after Circuit Mounting, so please pay attention to the touch on product.

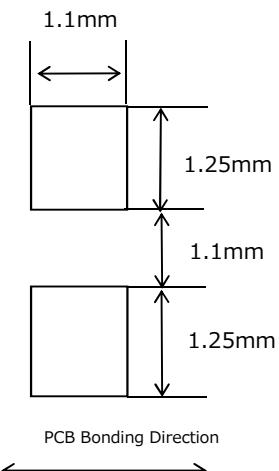
### 4-5. Soldering Pattern for Recommendation

We recommend the soldering pattern that shows on the right. It will be different according to mounting situation of circuit board, therefore, please concern before designing.

※The product has adopted the electrode structure that it should solder with back electrode of the product.

Thus, please be informed that the shape of electrode pin of solder fillet formation is not guaranteed.

The through hole on electrode surface is for conduction of front and rear electrodes but not for formation of solder fillet.

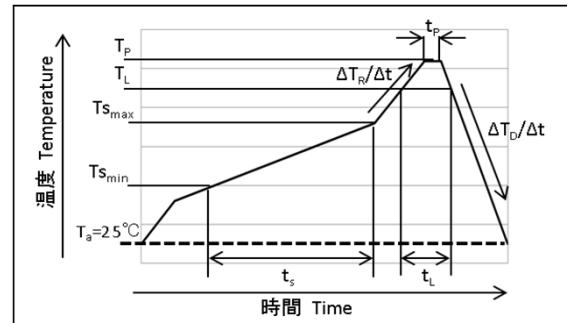


#### 4 – 6 . Reflow Profile

For reflow profile, please refer to the conditions below:(※)

##### ■ Meaning of marks, Conditions

Mark	Meanings	Conditions
$T_{S_{\max}}$	Maximum of pre-heating temperature	180°C
$T_{S_{\min}}$	Minimum of pre-heating temperature	140°C
$t_s$	Time from $T_{S_{\min}}$ to $T_{S_{\max}}$	Over 60sec.
$T_L$	Reference temperature	230~260°C
$t_L$	Retention time for $T_L$	Within 40sec.
$T_p$	Peak temperature	260°C(Max)
$t_p$	Time for peak temperature	Within 10sec.
$\Delta T_R/\Delta t$	Temperature rising rate	Under 3°C/sec.
$\Delta T_D/\Delta t$	Temperature decreasing rate	Over -3°C/sec.



※Above conditions are for reference. Therefore, evaluate by customer's own circuit boards and reflow furnaces before using, because stress from circuit boards and temperature variations of reflow furnaces vary by customer's own conditions.

#### 4 – 7 . Attention Points in Soldering Operation

This product was developed as a surface mount LED especially suitable for reflow soldering.

So reflow soldering is recommended. In case of implementing manual soldering, please take care of following points.

##### ①SOLDER USED

Sn-Cu, Sn-Ag-Cu, Sn-Ag-Bi-Cu

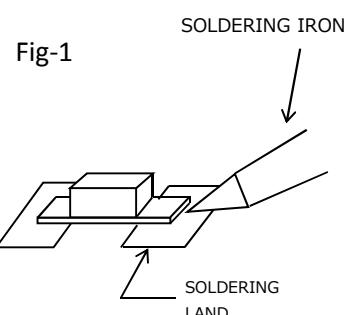
##### ②HAND SOLDERING CONDITION

LED products do not contain reinforcement material such as a glass fillers.

So thermal stress by soldering greatly influence its reliability.

Please keep following points for manual soldering.

ITEM	RECOMMENDED CONDITION
a) Heating method	Condition ) Temp. of iron top less than 400°C within 3 sec. Heating on PCB pattern, not direct to the LED. (Fig-1)
b) Handling after soldering	Please handle after the part temp. goes down to room temp.



#### 4 – 8 . Cleaning after Soldering

Please follow the conditions below if the cleaning is necessary after soldering.

Solvent	We recommend to use alcohols solvent such as, isopropyl alcohols
Temperature	Under 30°C within 3 minutes
Ultrasonic Cleaning	15W/ Below 1 liter (capacity of tank)
Drying	Under 100°C within 3 minutes

## Notes

- 1) The information contained herein is subject to change without notice.
- 2) Before you use our Products, please contact our sales representative and verify the latest specifications :
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